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C1  
7. (Amended) The method of bonding solder balls of claim 12, wherein said exposing comprises laser bonding the balls with their associated bond pads by fixing the position of the frame and moving a laser beam relative to the frame from ball-to-ball.

100417-100417  
8. (Amended) The method of bonding solder balls of claim 12, wherein said exposing comprises laser bonding the balls with their associated bond pads by fixing the position of a laser beam and moving the frame relative to the laser beam from ball-to-ball.

9. (Amended) The method of bonding solder balls of claim 12 further comprising moving the frame away from the substrate.

10. (Amended) The method of bonding solder balls of claim 12 further comprising after the exposing of the balls, moving the frame away from the substrate.

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11. (Amended) The method of bonding solder balls of claim 12,  
wherein:

said placing comprises placing individual solder balls within individual  
holes within the frame; and

said exposing of the balls comprises reflowing the solder balls while the  
balls are within their individual holes, and further comprising after said  
reflowing removing the frame from around the reflowed balls.

1000472-100001  
12. (Amended) A method of bonding solder balls to bond pads on a  
substrate comprising:

placing at least portions of a plurality of solder balls within a frame and  
in registered alignment with individual bond pads over a substrate by dipping  
the substrate into a volume of balls; and

while the ball portions are within the frame, exposing the balls to  
bonding conditions effective to bond the balls with their associated bond  
pads, wherein said placing comprises placing said ball portions on fluxless  
bond pad surfaces.

Cancel claim 13.

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14. (Amended) The method of claim 18, wherein the holes are sized to  
receive a majority portion of an associated solder ball.

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15. (Amended) The method of claim 18, wherein the holes are sized to receive a majority portion of only one associated solder ball.

16. (Amended) The method of claim 18, wherein said delivering of the individual balls comprises rolling at least one ball over a frame surface until the one ball drops into an associated hole.

17. (Amended) The method of claim 18, wherein said delivering of the individual balls comprises rolling a plurality of balls over a frame surface until individual balls drop into respective associated individual holes.

18. (Amended) A method of bonding solder balls to bond pads on a substrate comprising:

providing a frame having a plurality of holes sized to receive individual solder balls;

delivering individual balls into the holes from over the frame by dipping the frame into a volume of balls;

placing the balls into registered alignment, while the balls are in the holes, with a plurality of individual bond pads over a substrate; and

bonding the balls in the absence of flux with their individual associated bond pads, wherein said placing of the balls into registered alignment comprises moving the frame to proximate the substrate before any of the balls are delivered into the holes.

Cancel claim 19.

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20. (Amended) The method of claim 18, wherein the bonding of the balls comprises laser bonding the balls with their individual associated bond pads.

21. (Amended) The method of claim 18, wherein the bonding of the balls comprises laser bonding the balls with their individual associated bond pads by fixing the position of the frame and moving a laser beam relative to the frame from ball-to-ball.

22. (Amended) The method of claim 18, wherein the bonding of the balls comprises laser bonding the balls with their individual associated bond pads by fixing the position of a laser beam and moving the frame relative to the laser beam from ball-to-ball to effectuate the bonding.

Cancel claims 23-44.

## New Claims

45. A method of bonding balls of solder to bond pads on a substrate comprising:

contemporaneously retaining first and second balls of solder over different respective first and second bond pads on a substrate; and

with the first and second balls of solder so retained, sequentially exposing the first and second solder balls to bonding conditions in the absence of flux effective to (i) melt each of the first and second balls of solder and then (ii) cool each of the first and second molten balls of solder to bond each of the first and second balls of solder with their associated first and second bond pads.

46. The method of claim 45, wherein exposing comprises sequentially laser-bonding each of the first and second balls of solder.